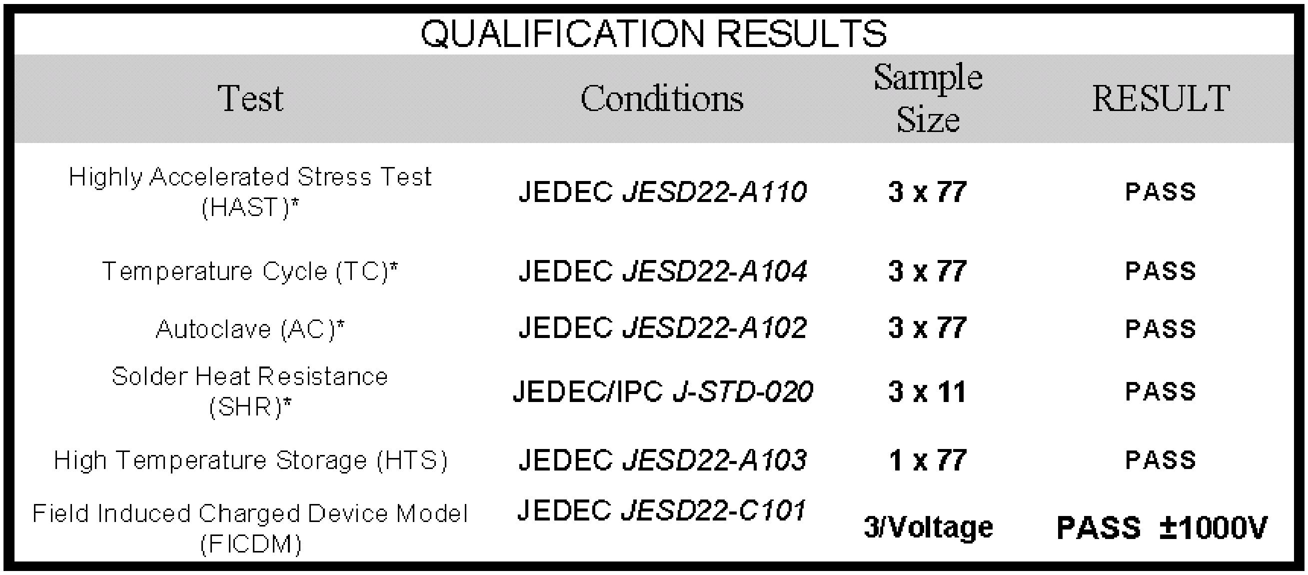
Material Set Change:

Package Material Set		Carsem	ASE Chungli
TSSOP 16L, 20L, 24L	Die Attach	Ablestik 84-1 LMISR4	Hitachi EN4900
	Mold Compound	Sumitomo 6600H	Hitachi CEL9240HF10AK
	Wire	0.8mil, 1.0mil and 1.2/1.3 mil Gold wire	0.8mil, 1mil and 1.2/1.3mil Gold Wire

Reliability Qualification Results of TSSOP 20_24L package at ASE Chungli (AET)



QUALIFICATION RESULTS

Test	Conditions	Sample Size	RESULT
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	3 x 77	PASS
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	3 x 77	PASS
Autoclave (AC)*	JEDEC *JESD22-A102*	3 x 77	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	3 x 11	PASS
High Temperature Storage (HTS)	JEDEC *JESD22-A103*	1 x 77	PASS
Field Induced Charged Device Model (FICDM)	JEDEC *JESD22-C101*	3/Voltage	PASS ±1000V

*Preconditioned per JEDEC/IPC J-STD-020

Reliability Qualification Results of TSSOP 16L package at ASE Chungli (AET)

QUALIFICATION RESULTS

Test	Conditions	Sample Size	RESULT
Highly Accelerated Stress Test (HAST)*	**JEDEC *JESD22-A110***	**3 x 77**	**PASS**
Temperature Cycle (TC)*	**JEDEC *JESD22-A104***	**3 x 77**	**PASS**
Autoclave (AC)*	**JEDEC *JESD22-A102***	**3 x 77**	**PASS**
Solder Heat Resistance (SHR)*	**JEDEC/IPC *J-STD-020***	**3 x 11**	**PASS**
High Temperature Storage (HTS)	**JEDEC *JESD22-A103***	**1 x 77**	**PASS**
Field Induced Charged Device Model (FICDM)	**JEDEC *JESD22-C101***	**3/Voltage**	**PASS ±1250V**

*Preconditioned per JEDEC/IPC J-STD-020